

LPA92-59

Conductor

Description

LPA92-59 is a screen printable gold conductor paste, designed to metallize punched or laser drilled through-holes in alumina substrates.

Key Features

- LPA92-59 contains a glass-filler, for good adhesion on to the inside wall of holes (through-holes)
- The viscosity has also been adjusted, for good vacuum through-hole printing
- It also works well as via-fills in multilayer dielectric, for interconnecting conductor layers



This picture does not show the packaging of LPA92-59 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Viscosity	30-50 Pas (25 °C, D = 75/s)
Alloy Ratio	100
Metal	Au

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